## BAS21M3T5G

## 250V High Voltage Switching Diode

The BAS21M3T5G device is a spin-off of our popular SOT-23 three-leaded device. It is designed for high voltage switching applications and is housed in the SOT-723 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

#### **Features**

- Reduces Board Space
- This is a Halide-Free Device
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

#### **MAXIMUM RATINGS** (EACH DIODE)

Rating	Symbol	Value	Unit
Reverse Voltage	$V_{R}$	250	Vdc
Forward Current	IF	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	625	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	265 2.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	470	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	640 5.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	195	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.



#### ON Semiconductor®

http://onsemi.com

## 250 V HIGH VOLTAGE SWITCHING DIODE



#### MARKING DIAGRAM



SOT-723 CASE 631AA STYLE 2



AM = Specific Device Code M = Date Code

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
BAS21M3T5G	SOT-723 (Pb-Free)	8000 / Tape & Reel
NSVBAS21M3T5G	SOT-723 (Pb-Free)	8000 / Tape & Reel

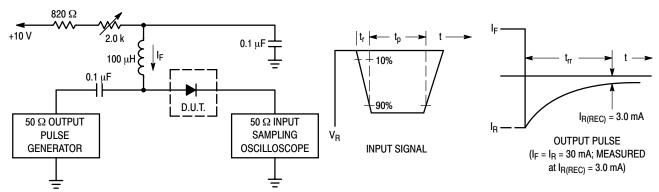
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### BAS21M3T5G

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Reverse Voltage Leakage Current $(V_R = 200 \text{ Vdc})$ $(V_R = 200 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I <sub>R</sub>		0.1 100	μAdc
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)	V <sub>(BR)</sub>	250	=	Vdc
Forward Voltage (I <sub>F</sub> = 100 mAdc) (I <sub>F</sub> = 200 mAdc)	V <sub>F</sub>	- -	1.0 1.25	Vdc
Diode Capacitance (V <sub>R</sub> = 0, f = 1.0 MHz)	C <sub>D</sub>	-	5.0	pF
Reverse Recovery Time ( $I_F = I_R = 30 \text{ mAdc}$ , $I_{R(REC)} = 3.0 \text{ mAdc}$ , $R_L = 100$ )	t <sub>rr</sub>	-	50	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



Notes: 1. A 2.0  $k\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 30 mA.

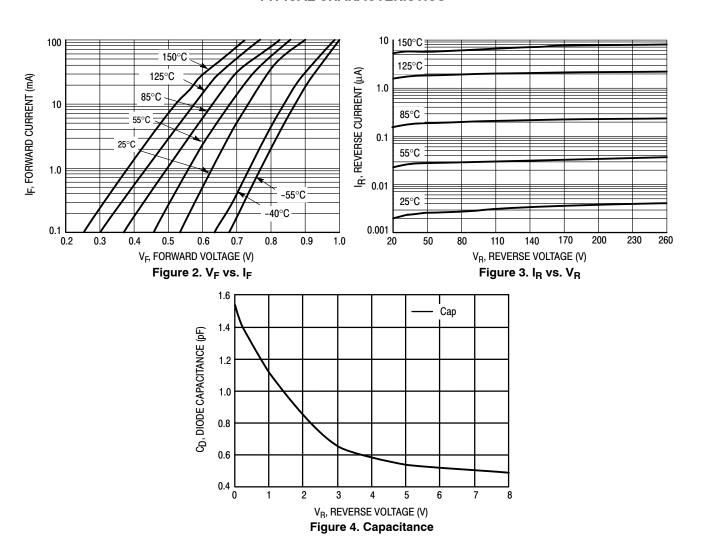
2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 30 mA.

3.  $t_p * t_{rr}$ 

Figure 1. Recovery Time Equivalent Test Circuit

#### BAS21M3T5G

#### **TYPICAL CHARACTERISTICS**





SOT-723 CASE 631AA-01 ISSUE D

**DATE 10 AUG 2009** 

## NOTES:

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD
- FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.45	0.50	0.55
b	0.15	0.21	0.27
b1	0.25	0.31	0.37
С	0.07	0.12	0.17
D	1.15	1.20	1.25
E	0.75	0.80	0.85
е	0.40 BSC		
ΗE	1.15	1.20	1.25
L	0.29 REF		
12	0.15	0.20	0.25

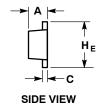
### **L2** 0.15 0.20 0.25 **GENERIC** MARKING DIAGRAM\*

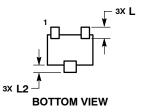


= Specific Device Code XX Μ = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

# -X-2X b ⊕ 0.08 X Y **TOP VIEW**

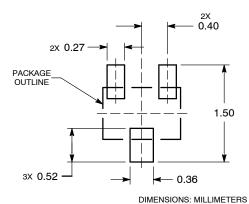




STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR STYLE 2: PIN 1. ANODE 2. N/C 3. CATHODE STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE

STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE STYLE 5: PIN 1. GATE 2. SOURCE 3. DRAIN

**RECOMMENDED SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOT-723		PAGE 1 OF 1

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